



# THE DATASHEET OF SFH 4550-FW AN18



# Infrared Emitter (850 nm)

## Version 1.6

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### SFH 4550



#### Features:

- High Power Infrared LED
- Narrow emission angle  $\pm 3^\circ$
- Very high radiant intensity
- UL version available ( details & test conditions on request)

#### Applications

- Infrared Illumination for cameras
- Data transmission
- Sensor technology
- Smoke detectors

#### Notes

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

#### Ordering Information

Type:	Radiant Intensity $I_e$ [mW/sr] $I_F= 100 \text{ mA}, t_p= 20 \text{ ms}$	Ordering Code
SFH 4550	1100 ( $\geq 630$ )	Q65110A1772
SFH 4550 E9548 (UL)	1100 ( $\geq 630$ )	Q65110A8097
SFH 4550-EWFW	630 ... 2000	Q65110A7758

*Note:* Measured at a solid angle of  $\Omega = 0.001 \text{ sr}$

**Maximum Ratings** ( $T_A = 25\text{ °C}$ )

Parameter	Symbol	Values	Unit
Operating temperature range	$T_{op}$	-40 ... 100	°C
Storage temperature range	$T_{stg}$	-40 ... 100	°C
Reverse voltage	$V_R$	5	V
Forward current	$I_F$	100	mA
Surge current ( $t_p \leq 100\ \mu\text{s}$ , $D = 0$ )	$I_{FSM}$	1	A
Power consumption	$P_{tot}$	180	mW
ESD withstand voltage (acc. to ANSI/ ESDA/ JEDEC JS-001 - HBM)	$V_{ESD}$	2	kV
Thermal resistance junction - ambient <sup>1) page 8</sup>	$R_{thJA}$	450	K / W

**Characteristics** ( $T_A = 25\text{ °C}$ )

Parameter	Symbol	Values	Unit
Peak wavelength ( $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$ )	(typ) $\lambda_{peak}$	860	nm
Centroid wavelength ( $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$ )	(typ) $\lambda_{centroid}$	850	nm
Spectral bandwidth at 50% of $I_{max}$ ( $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$ )	(typ) $\Delta\lambda$	30	nm
Half angle	(typ) $\varphi$	$\pm 3$	°
Dimensions of active chip area	(typ) L x W	0.3 x 0.3	mm x mm
Rise and fall time of $I_e$ ( 10% and 90% of $I_{e\ max}$ ) ( $I_F = 100\text{ mA}$ , $R_L = 50\ \Omega$ )	(typ) $t_r, t_f$	12	ns
Forward voltage ( $I_F = 100\text{ mA}$ , $t_p = 20\text{ ms}$ )	(typ (max)) $V_F$	1.5 ( $\leq 1.8$ )	V
Forward voltage ( $I_F = 1\text{ A}$ , $t_p = 100\ \mu\text{s}$ )	(typ (max)) $V_F$	2.4 ( $\leq 3$ )	V
Reverse current ( $V_R = 5\text{ V}$ )	$I_R$	not designed for reverse operation	$\mu\text{A}$
Total radiant flux ( $I_F=100\text{ mA}$ , $t_p=20\text{ ms}$ )	(typ) $\Phi_e$	70	mW

Parameter		Symbol	Values	Unit
Temperature coefficient of $I_e$ or $\Phi_e$ ( $I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$ )	(typ)	$TC_I$	-0.5	% / K
Temperature coefficient of $V_F$ ( $I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$ )	(typ)	$TC_V$	-0.7	mV / K
Temperature coefficient of wavelength ( $I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$ )	(typ)	$TC_\lambda$	0.3	nm / K

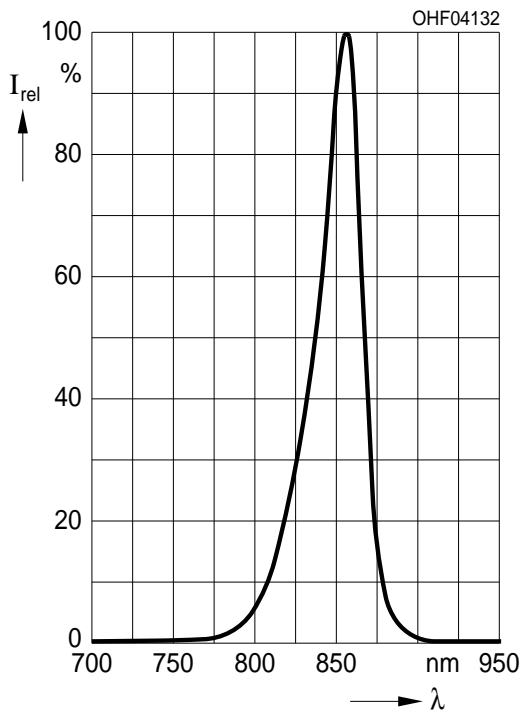
**Grouping** ( $T_A = 25 \text{ }^\circ\text{C}$ )

Group	Min Radiant Intensity $I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$ $I_{e, \text{min}}$ [mW / sr]	Max Radiant Intensity $I_F = 100 \text{ mA}$ , $t_p = 20 \text{ ms}$ $I_{e, \text{max}}$ [mW / sr]	Typ Radiant Intensity $I_F = 1 \text{ A}$ , $t_p = 25 \text{ } \mu\text{s}$ $I_{e, \text{typ}}$ [mW / sr]
SFH 4550-EW	630	1250	7500
SFH 4550-FW	1000	2000	12000
SFH 4550-GW	1600	3200	19000

Note: Measured at a solid angle of  $\Omega = 0.001 \text{ sr}$   
Only one group in one packing unit (variation lower 2:1).

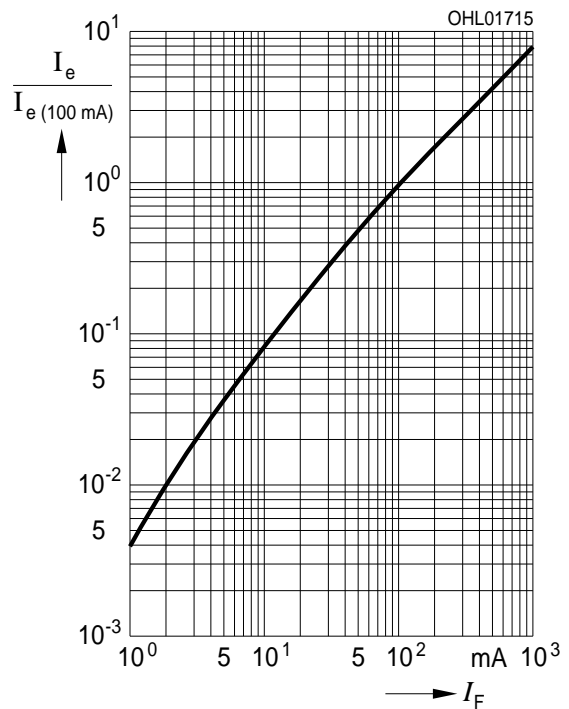
**Relative Spectral Emission** <sup>2) page 8</sup>

$I_{\text{rel}} = f(\lambda)$ ,  $T_A = 25 \text{ }^\circ\text{C}$



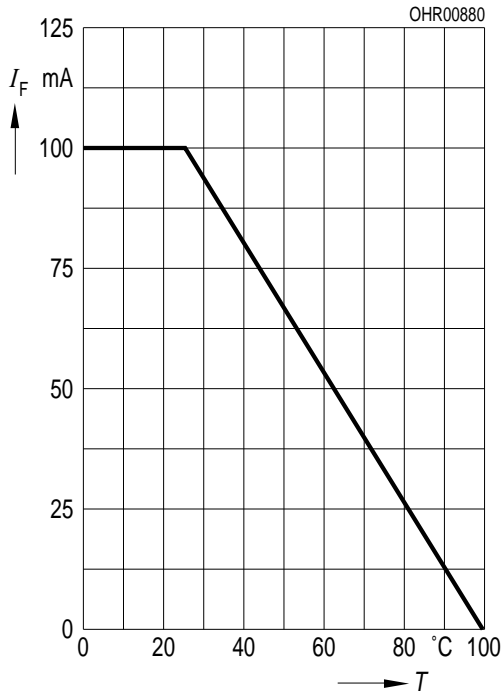
**Radiant Intensity** <sup>2) page 8</sup>

$I_e / I_e(100 \text{ mA}) = f(I_F)$ , single pulse,  $t_p = 25 \text{ } \mu\text{s}$ ,  $T_A = 25 \text{ }^\circ\text{C}$



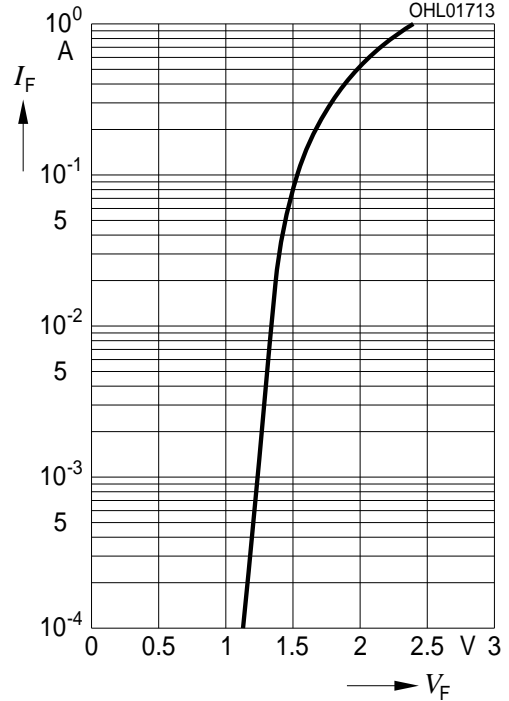
**Max. Permissible Forward Current**

$I_{F, \max} = f(T_A), R_{thJA} = 450 \text{ K/W}$



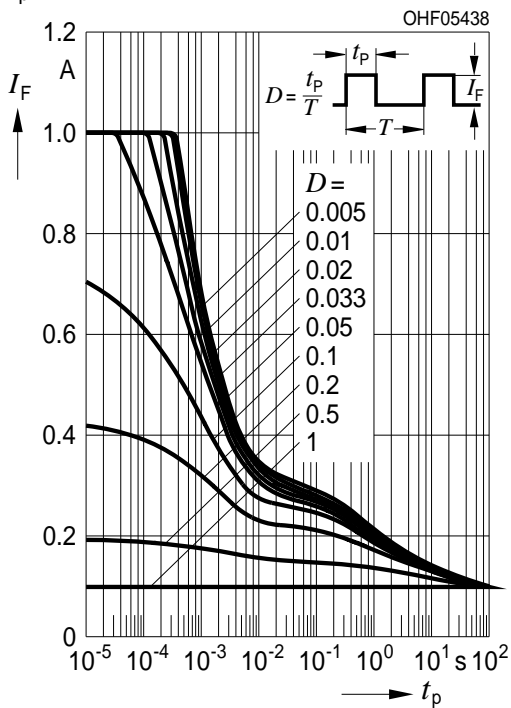
**Forward Current** <sup>2) page 8</sup>

$I_F = f(V_F), \text{ single pulse, } t_p = 100 \mu\text{s}, T_A = 25^\circ\text{C}$



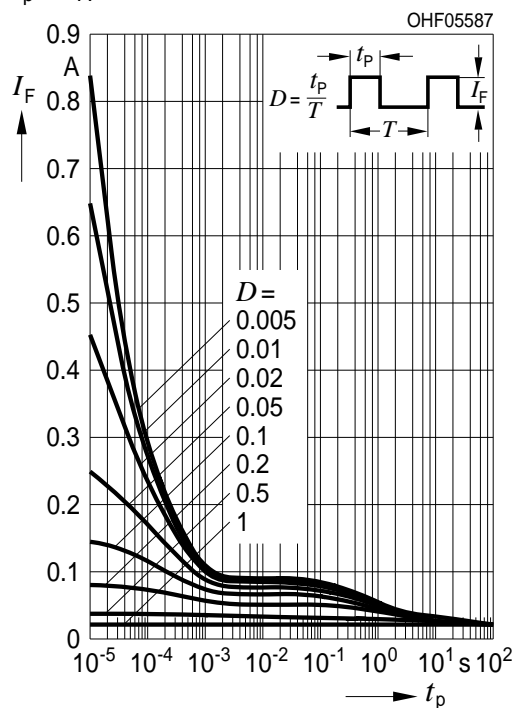
**Permissible Pulse Handling Capability**

$I_F = f(t_p), T_A = 25^\circ\text{C}, \text{ duty cycle } D = \text{parameter}$



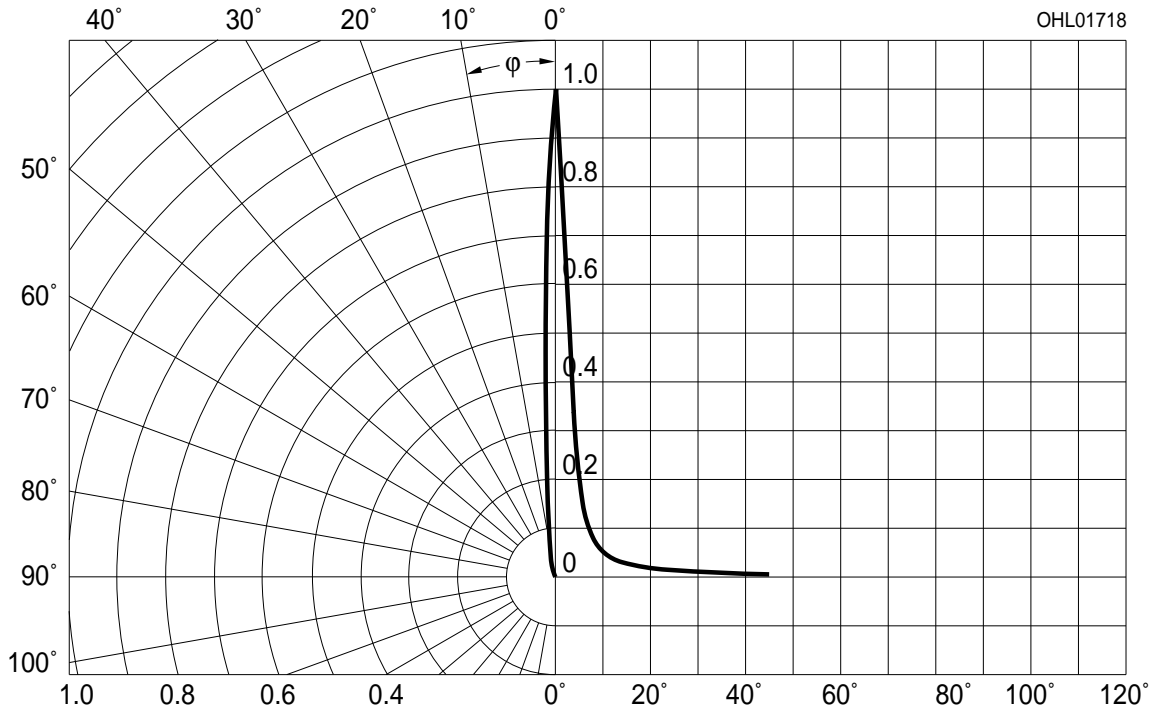
**Permissible Pulse Handling Capability**

$I_F = f(t_p), T_A = 85^\circ\text{C}, \text{ duty cycle } D = \text{parameter}$

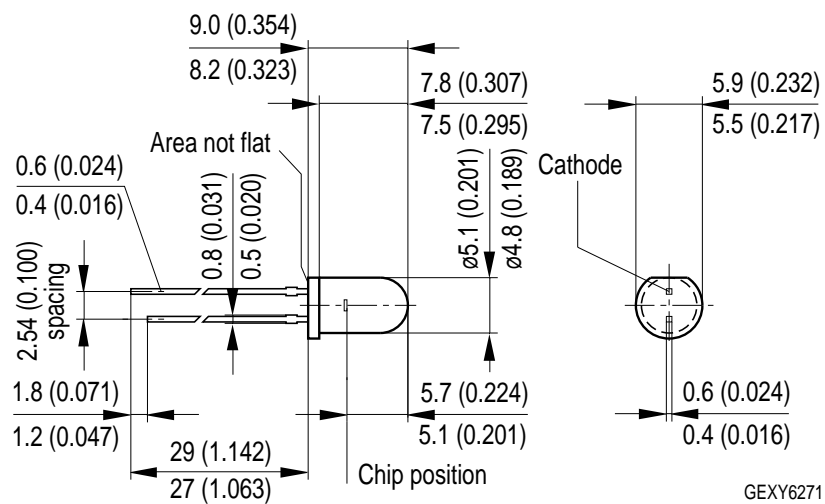


**Radiation Characteristics** <sup>2) page 8</sup>

$I_{rel} = f(\phi), T_A = 25^\circ\text{C}$



**Package Outline**



*Dimensions in mm (inch).*

**Package**

5mm Radial (T 1 3/4), Epoxy

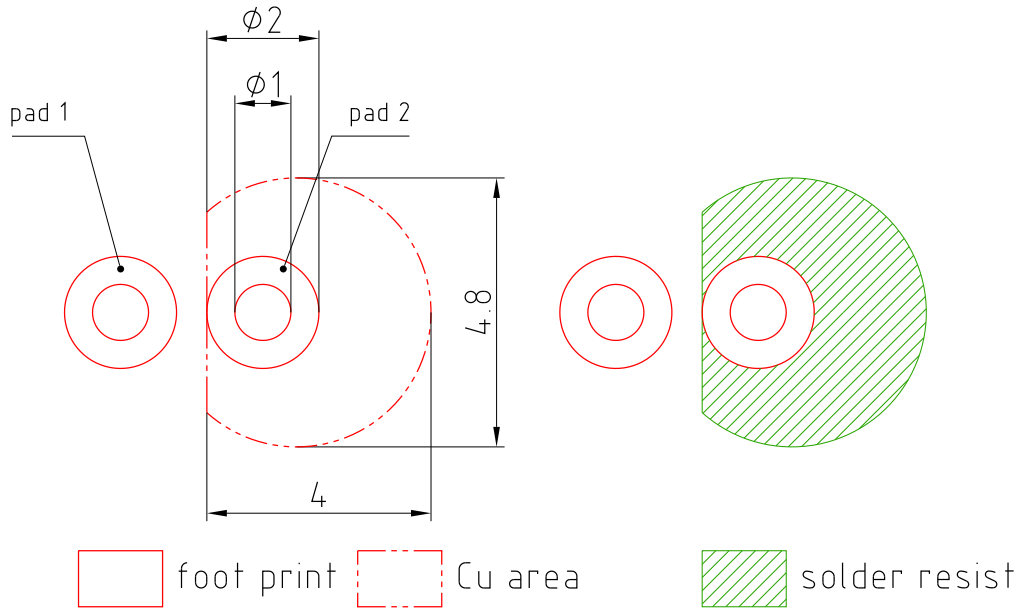
**Approximate Weight:**

0.3 g

**Note**

Packing information is available on the internet (online product catalog).

**Recommended Solder Pad**



E062.3010.188-01

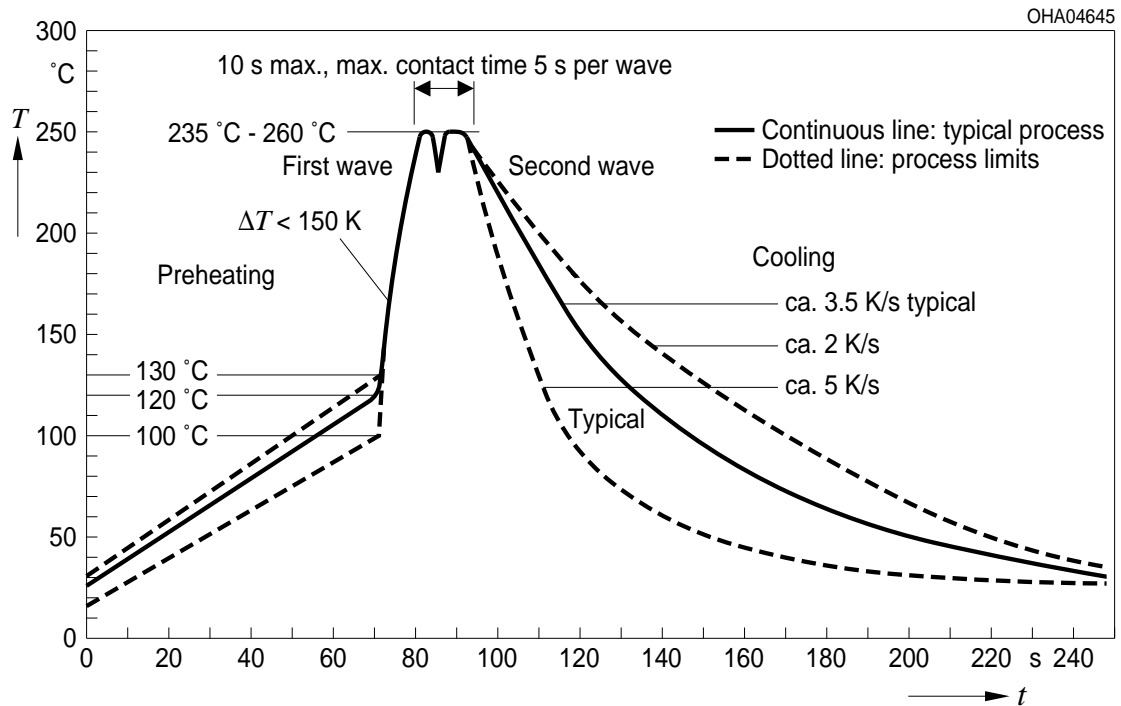
Dimensions in mm.

**Note:**

pad 1: cathode

**TTW Soldering**

IEC-61760-1 TTW

**Disclaimer**

Language english will prevail in case of any discrepancies or deviations between the two language wordings.

**Attention please!**

The information describes the type of component and shall not be considered as assured characteristics.

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\*\*) Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health and the life of the user may be endangered.

**Glossary**

- 1) **Thermal resistance:** junction -ambient, mounted on PC-board (FR4), padsize 16 mm<sup>2</sup> each
- 2) **Typical Values:** Due to the special conditions of the manufacturing processes of LED, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

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